

Description

APL0501BNCSA device is a low R_{ON} MOSEFT controlled by external logic pin, allowing optimization of battery life, and portable device autonomy. It includes a P-channel MOSFET that operates over an input voltage range of 1.2V to 5.5V. An on/off input (ON) controls the switch that can interface with low voltage control signals. APL0501BNCSA is packaged in WLCSP-4 with 0.4mm pitch. It is characterized for operation over the free-air temperature range of -40° C to 85°C.

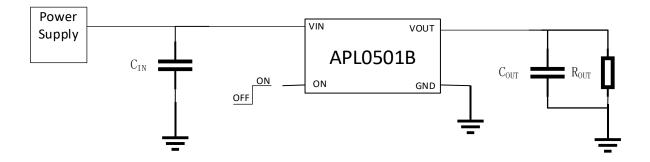
Applications

- Cellular Phones
- GPS Devices
- Digital Cameras
- Peripheral Ports
- Portable Instrumentation
- RF Modules
- Personal Digital Assistants (PDAs)
- MP3 Players

Features

- Low-Input Voltage: 1.2V to 5.5V
- Ultra-Low ON-State Resistance
 - R_{ON} =48m Ω at VIN=5.0V
 - R_{ON} =53m Ω at VIN=4.2V
 - R_{ON} =56m Ω at VIN=3.6V
 - \bullet R_{ON}=67m Ω at VIN=2.5V
 - R_{ON} =87mΩ at VIN=1.8V
 - R_{ON} =160m Ω at VIN=1.2V
- DC Current Up to 2.0A
- Ultra-Low Quiescent Current: 80nA at 1.8V
- Ultra-Low Shutdown Current: 5nA at 1.8V
- Low Control Input Thresholds Enable Use of 1.2V/1.8V/3.6V/4.2V/5.0V Logic
- Controlled Slew Rate to Avoid Inrush Current
- Reverse Current Protection
- Package: WLCSP-4 (0.4mm Pitch)

Typical Application



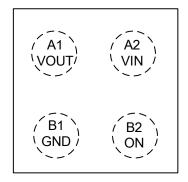


Package and Order Information

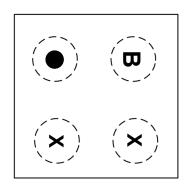
Part Number	Package	Temperature	Temperature Packaging	
	Description	Range	Option	Information
APL0501BNCSA	WLCSP-4	-40°C ~ 85°C	3000/Tape & Reel	BXX

Pin Configuration and Top Mark

Top View



Top Mark

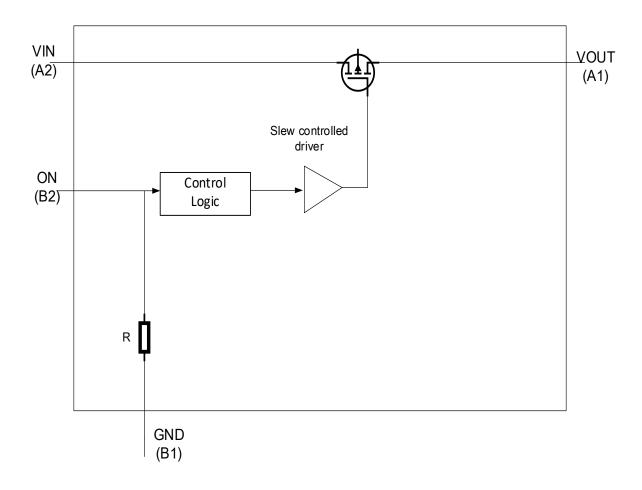


XX = Production Tracing Code

Pin Assignments

Name	NO.	Description		
VOUT	A1	Switch output		
VIN	A2	Switch input, a bypass capacitor should be connected to ground together with it		
GND	B1	Ground		
ON	B2	Switch control input, active high		

Functional Block Diagram





Absolute Maximum Ratings (T_A = 25°C unless otherwise specified)

Symbol	Parameter	Rating	Unit	
V _{IN}	Input voltage	-0.3 to 6	V	
V _{OUT}	Output voltage	V _{IN} + 0.3	V	
V _{ON}	Input voltage	-0.3 to 6	V	
P _D	Power dissipation at T _A =25°C	0.48	W	
	Maximum continuous switch current (VIN≥1.8V)	2		
I _{MAX}	Maximum continuous switch current (1.2V≤VIN<1.8V)	1.5	Α	
T _A	Operating free air temperature range	-40 to 85	°C	
T _{LEAD}	Maximum lead temperature (10s soldering time)	300	°C	
T _{STG}	Storage temperature	-45 to 145	°C	
θ_{JA}	Thermal Resistance	190	°C/W	
ESD	HBM: All Pins	±4000	V	
ESD	CDM	±1000	V	
Latch up		±200	mA	

Recommend Operating Conditions

Symbol	Parameter	Rating	Unit
Vin	Input voltage range	1.2 to 5.5	V
Vоит	Output voltage range	Vin	V
Cin	Input capacitor	1	μF



Electrical Characteristics ($T_A = 25$ °C unless otherwise specified)

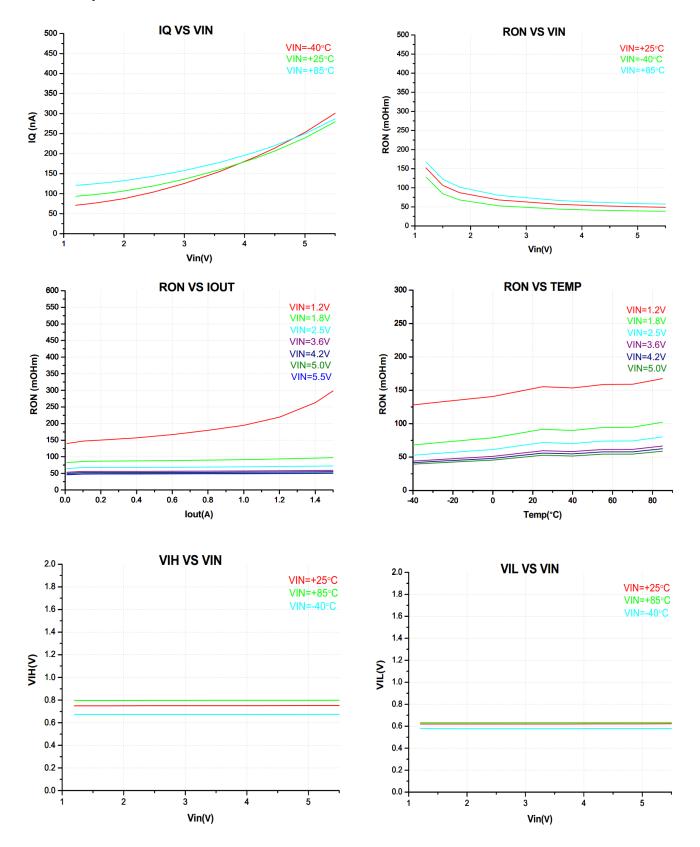
Symbol	Parameter	Condition	ons	Min.	Тур.	Max.	Unit
	Quiescent current		V _{IN} =1.2V	40	75	130	nA
			V _{IN} =1.8V		80		
Ιq		Iout=0, Vin=Von	V _{IN} =3.6V	90	119	250	
			V _{IN} =4.2V		142		
			V _{IN} =5.0V	150	188	350	
			V _{IN} =1.2V		5	20	
			V _{IN} =1.8V		5		
Isp	OFF-state supply current	V _{ON} =GND, V _{OUT} =Open	V _{IN} =3.6V		5.5	30	nA
		V ₀₀₁ -Open	V _{IN} =4.2V		5.5		
			V _{IN} =5.0V		5.5	50	
	OFF-state supply current	Von=GND, Vout=0	V _{IN} =1.2V		6.5		nA
			V _{IN} =1.8V		6.5		
Ilkg			V _{IN} =3.6V		8		
			V _{IN} =4.2V		10		
			V _{IN} =5.0V		16		
	ON-state resistance	louт=-200mA	V _{IN} =1.2V	140	160	190	
			V _{IN} =1.8V		87		- mΩ
D			V _{IN} =2.5V		68		
Ron			V _{IN} =3.6V		56		
			V _{IN} =4.2V		53		
			V _{IN} =5.0V	30	48	70	
lrev	Reverse current during disable	V _{OUT} =5.0V, V _{ON} =0, V _{IN} =0V			8		nA
Ron_pd	ON pull down resistance				100		ΜΩ
ViH	High level input voltage	V _{IN} =1.2V to 5.5V		1.0			٧
VIL	Low level input voltage	V _{IN} =1.2V to 5.5V				0.5	٧



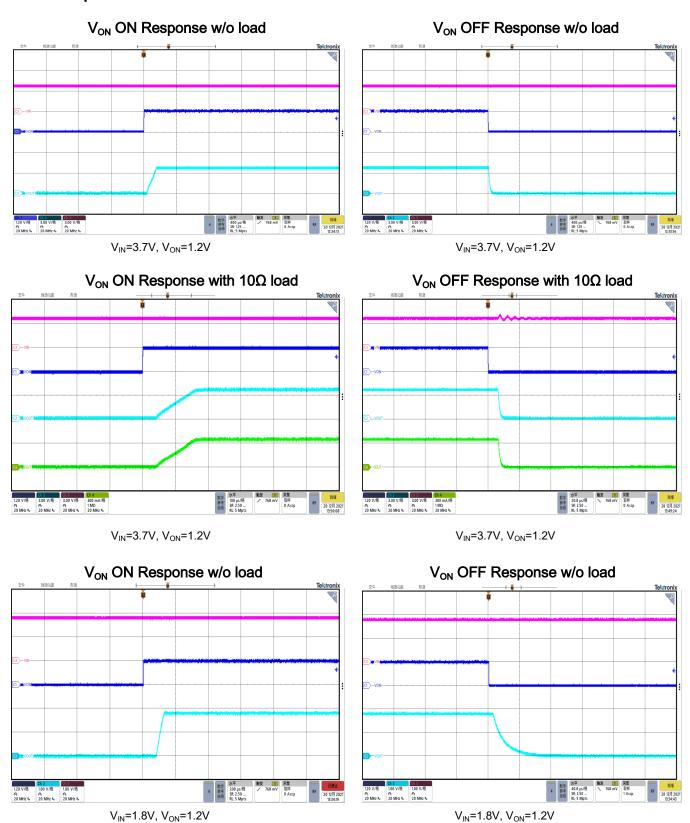
Switching Characteristics (T_A = 25°C unless otherwise specified)

Symbol	Parameter	Conditions		Min.	Тур.	Max.	Unit
V _{IN} =1.2V							
t _{ON}	Turn on time	R _L =500Ω	C _L =0.1µF		162		μs
t _{OFF}	Turn off time	R _L =500Ω	C _L =0.1µF		40		μs
t _R	VOUT rise time	R _L =500Ω	C _L =0.1µF		7		μs
t _F	VOUT fall time	R _L =500Ω	C _L =0.1µF		123		μs
V _{IN} =1.8V							
t _{ON}	Turn on time	R _L =500Ω	C _L =0.1µF		70		μs
t _{OFF}	Turn off time	R _L =500Ω	C _L =0.1µF		44		μs
t _R	VOUT rise time	R _L =500Ω	C _L =0.1µF		10		μs
t _F	VOUT fall time	R _L =500Ω	C _L =0.1µF		122		μs
V _{IN} =3.6V							
t _{ON}	Turn on time	R _L =500Ω	C _L =0.1µF		41		μs
t _{OFF}	Turn off time	R _L =500Ω	C _L =0.1µF		46		μs
t _R	VOUT rise time	R _L =500Ω	C _L =0.1µF		26		μs
t _F	VOUT fall time	R _L =500Ω	C _L =0.1µF		132		μs
V _{IN} =4.2V							
t _{ON}	Turn on time	R _L =500Ω	C _L =0.1µF		40		μs
t _{OFF}	Turn off time	R _L =500Ω	C _L =0.1µF		44		μs
t _R	VOUT rise time	R _L =500Ω	C _L =0.1µF		32		μs
t _F	VOUT fall time	R _L =500Ω	C _L =0.1µF		135		μs
V _{IN} =5V							
t _{ON}	Turn on time	R _L =500Ω	C _L =0.1µF		42		μs
t _{OFF}	Turn off time	R _L =500Ω	C _L =0.1µF		47		μs
t _R	VOUT rise time	R _L =500Ω	C _L =0.1µF		37		μs
t _F	VOUT fall time	R _L =500Ω	C _L =0.1µF		136		μs



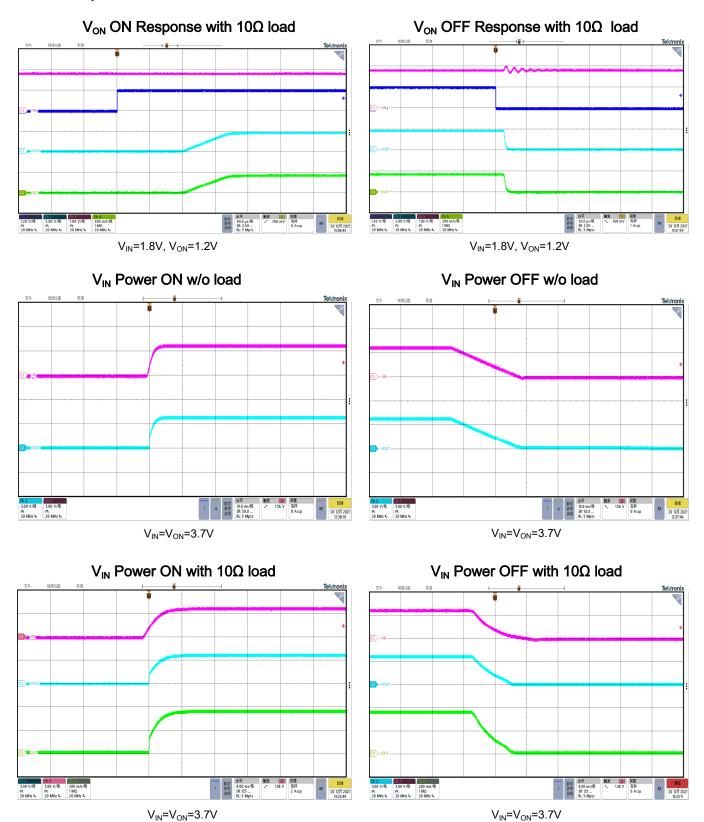






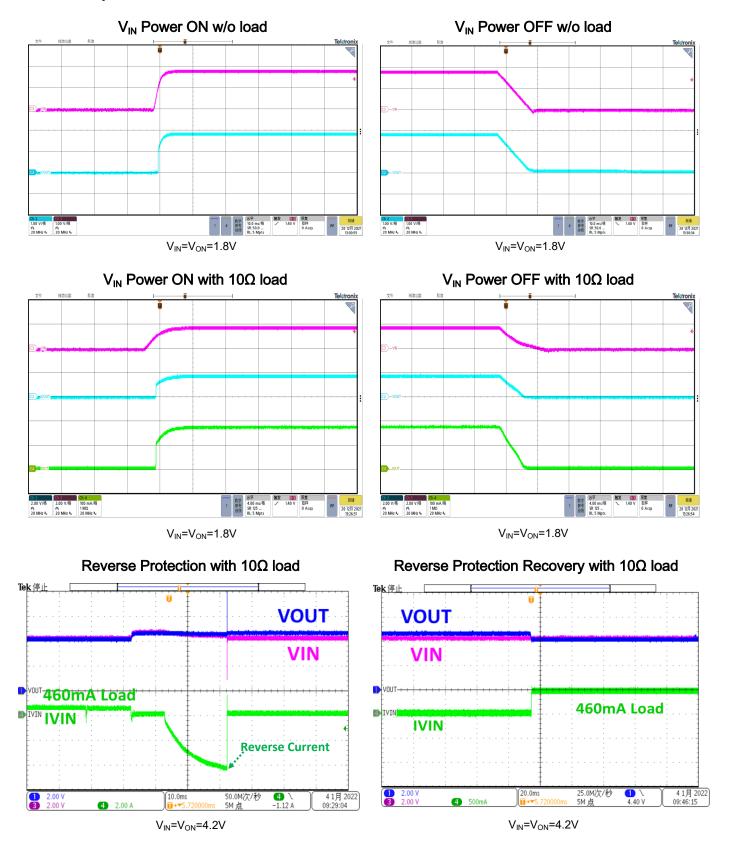
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Functional Description

Device Operation

The APL0501BNCSA is a low on-resistance (R_{ON}) load switch with controlled turn on, up to 1.5A output current. It contains a P-channel MOSFET and can be turned on with a wide range application of battery from 1.2V to 5.5V. An on/off input (ON) controls the switch, which can interface with low-threshold 1.2V GPIO control signal.

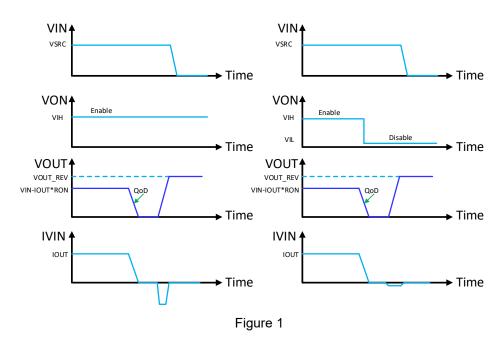
ON/OFF Control

The pin of ON controls the state of the switch. ON is active HI pin and has a low threshold making it capable of interfacing with low voltage GPIO control signals. It can be used with any microcontroller with 1.2V, 1.8V, 2.5V, 3.3V GPIOs. Applying VIH on the ON pin will put the switch in the on-state and VIL will put the switch in the off-state.

ON (Control Input)	VIN to VOUT		
L	OFF		
н	ON		

Reverse Current Protection

The device includes a reverse current protection circuit, which stops a reverse current flowing from the VOUT pin to the VIN or GND pin when the voltage on VOUT becomes higher than VIN. This feature is particularly useful when the output of device needs to be driven by another voltage source, whichever device is both disabled and enabled (for example in a power multiplexer application). In order for this feature to work, device has to be disabled, and either of the following conditions shall be met: VIN > 1.2V or VOUT > 1.2V. Meanwhile considering of heat dissipation, VIN input voltage should be limited less than 4.8V voltage when VON is active high.





Functional Description (Continued)

Input Bypass Capacitor

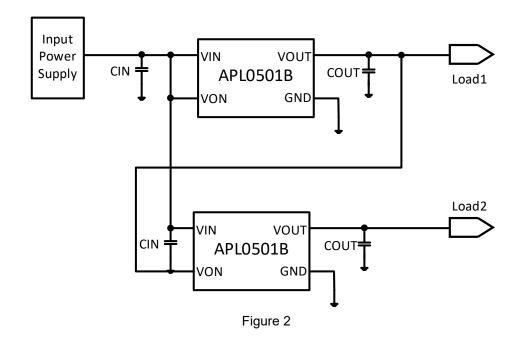
A low ESR ceramic capacitor, X5R or X7R, needs to be placed between VIN and GND to limit the voltage drop on the input supply caused by transient in-rush currents. A typical $1\mu F$ ceramic capacitor, C_{IN} , placed close to the pins is usually needed. C_{IN} 's higher values can be used to further reduce the voltage drop during high current output application. It is recommended that the input capacitor is approximately 10 times higher than the output capacitor to prevent excessive voltage drop when switching heavy loads.

Output Bypass Capacitor

A low ESR ceramic capacitor, X5R or X7R, should be placed between VOUT and GND. A $0.1\mu F$ ceramic capacitor that is placed close to the IC pins is usually sufficient. This capacitor will prevent parasitic board inductances from forcing VOUT below GND when the switch turns off. It is recommended that C_{IN} is 10times higher than C_{OUT} so that once the switch is turned on, COUT can be charged up to VIN without VIN dropping significantly.

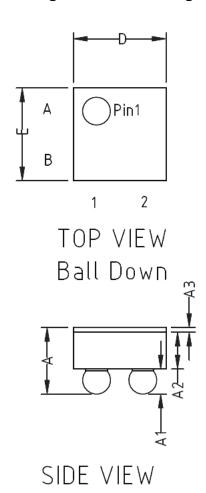
Power Supply Sequencing without a GPIO Input Control Port

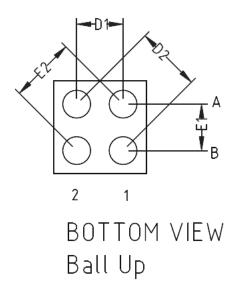
In many terminal devices, each module needs to be powered up in a pre-determined manner. The device can solve the power sequencing problem without increasing any complexity to the overall system. Figure 2 shows the configuration required to power up the two modules in a fixed sequence. The output of the first load switch is tied to the enable of the second load switch, so when load1 is powered, the second load switch is enabled and load2 is powered.





Package Outline Drawing





				Unit:mm
		NO.	Mean	Tolerance
Top Thickness	A	0. 449	± 0.036	
Ball Height+UBM T	hickness	A1	0. 194	\pm 0.023
Wafer/Grinding Th	ickness	A2	0. 215	\pm 0.0125
Backside Coating Thickness		A3	0. 04	±0.005
Pkg Die Size	X	D	0.775	± 0.025
rkg Die Size	Y	Е	0.775	± 0.025
Ball Size afer re	flow	F	0. 268	\pm 0.020
		D1	0.4	NA
D-11 D:4-1	D2	0. 565	NA	
Ball Pitch		E1	0.4	NA
		E2	0. 565	NA

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